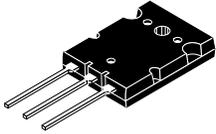


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

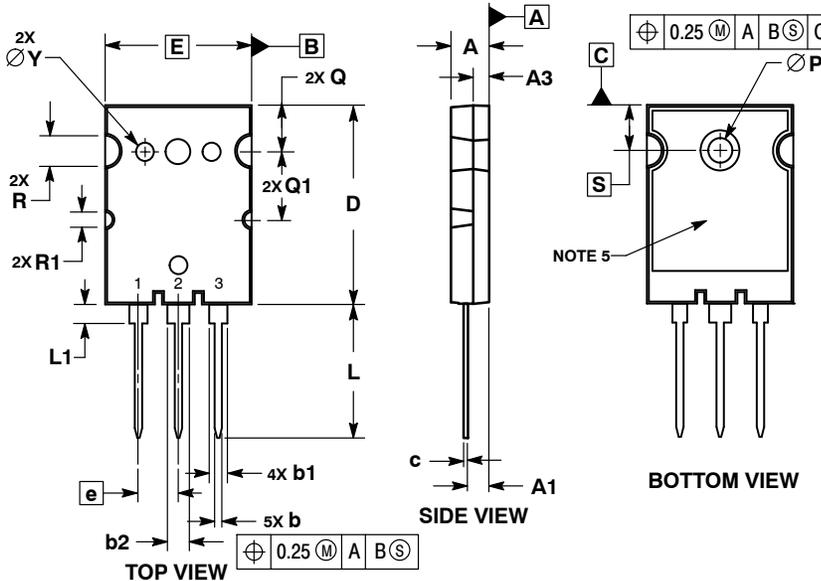
ON Semiconductor®



TO-264, 3-LEAD
CASE 340AJ
ISSUE O

DATE 04 FEB 2013

SCALE 1:2

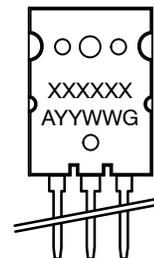


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES BETWEEN 2.50 AND 3.81 FROM THE LEAD TIP.
4. DIMENSION S APPLIES TO THE MOUNTING HOLE ($\varnothing P$). DIMENSION Q APPLIES TO THE NOTCHES ($2X R$).
5. THERMAL PAD SIZE AND SHAPE MAY VARY WITHIN THE AREA DEFINED BY DIMENSIONS D AND E .

DIM	MILLIMETERS	
	MIN	MAX
A	4.80	5.20
A1	2.50	3.10
A3	2.00	REF
b	0.90	1.25
b1	2.50	REF
b2	3.00	REF
c	0.50	0.85
D	25.60	26.40
E	19.80	20.20
e	5.45	BSC
L	16.80	18.20
L1	2.30	2.70
P	3.10	3.50
Q	5.80	6.20
Q1	8.80	9.20
R	4.00	REF
R1	2.00	REF
S	9.00	BSC
Y	1.80	REF

GENERIC MARKING DIAGRAM*



- XXXXXX = Specific Device Code
- A = Assembly Location
- YY = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present.

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NEW STANDARD:		
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